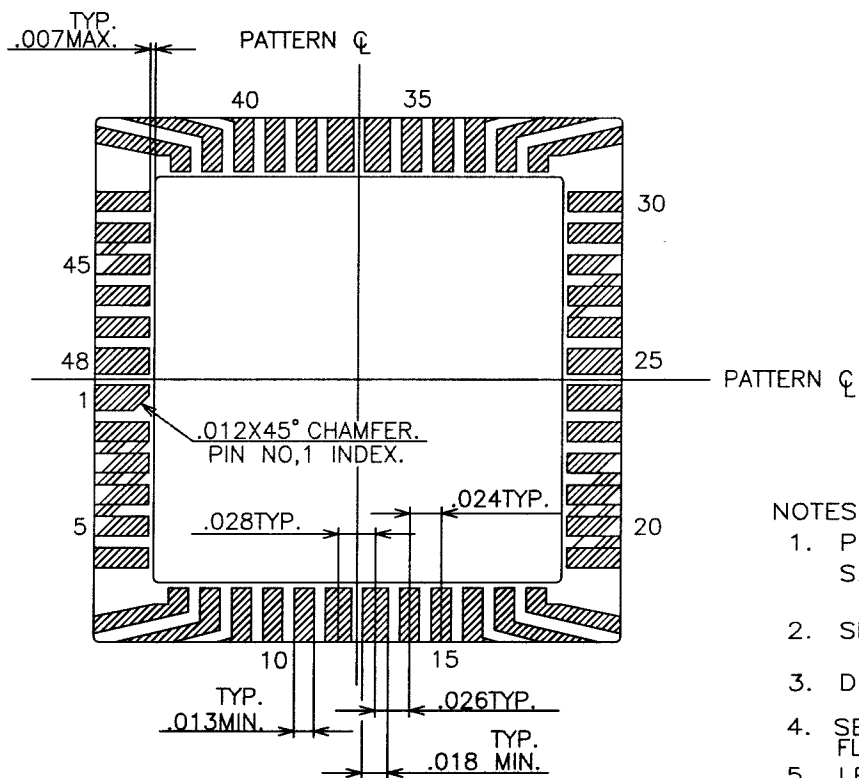


SB048T934-1 S=C
D=C

MODIFICATION	NAME	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
	48 LEAD SIDE BRAZED PACKAGE	±.005	H.Y	K.O	M.M K.M	DEC.4.'87
	SCALE 4/1					
	MATERIAL AS INDICATED					
△	ADDED: .050±.025, .040 MAX., .005MIN.					
△	REDRAWN (CONVERTED CAD DATA)					
	CHANGED					
	DATE	DRAWN	CHECKED	APPROVED		
	FEB.17.'97	S.TH	A.F K.I	T.A		
	AUG.20.'93	H.SH	H.SU S.F	T.A		
	KYOCERA		KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO. KD-S87934-B SHEET 1/2	



BONDING PATTERN

NOTES :

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.1 ? MAX. AT PIN NO.11,12,13,14,35,36,37,38
0.25 ? MAX. AT PIN NO.1,2,23,24,25,26,47,48
OTHER LESS THAN 0.7 ? MAX.

MODIFICATION						NAME 48 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN H.Y	CHECKED K.O	APPROVED M.M / K.M	DATE DEC.4.'87
						SCALE 10 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
Δ	REDRAWN (CONVERTED CAD DATA)	AUG.20.'93	H.SH	H.SU / S.F	T.A						
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-S87934-B		SHEET 2/2